

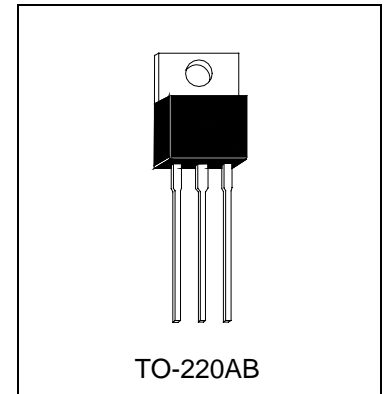


# HBT139XE

Three Quadrant Triac

## Description

Passivated, sensitive gate triacs in a plastic envelope, intended for use in general purpose bidirectional switching and phase control applications, where high sensitivity is required in all four quadrants.



## Quick Reference Data

Part No.	$V_{DRM}(V)$	$I_{T(RMS)}(A)$	$I_{TSM}(A)$	Quadrant
HBT139DE	600	16	140	I - II - III

## Pin Configuration

Pin	Description		Symbol
1	Main terminal 1		
2	Main terminal 2		
3	Gate		
tab	Main terminal 2		

## Limiting Values

Symbol	Parameter	Min.	Max.	Units
$V_{DRM}$	Repetitive peak off-state voltages	-	600	V
$I_{T(RMS)}$	RMS on-state current	-	16	A
$I_{TSM}$	Non-repetitive peak on-state current	-	140	A
$I^2t$	$I^2t$ for fusing	-	98	A <sup>2</sup> S
$dI_T/dt$	Repetitive rate of rise of on-state current after triggering T2+ G+	-	50	A/us
	T2+ G-	-	50	A/us
	T2- G-	-	50	A/us
	T2- G+	-	-	A/us
$I_{GM}$	Peak gate current	-	2	A
$V_{GM}$	Peak gate voltage	-	10	V
$P_{GM}$	Peak gate power	-	5	W
$P_{G(AV)}$	Average gate power	-	0.5	W
Tstg	Storage Temperature Range	-	150	°C
Tj	Operating junction temperature	-40	125	°C



### Static Characteristics (Ta=25°C)

Symbol	Parameter	Conditions	Rank	Unit
			V	
I <sub>GT</sub>	Gate Trigger Current	V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2+ G+	25	mA
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2+ G-	25	mA
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2- G-	25	mA
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2- G+	-	mA
I <sub>L</sub>	Latching Current	V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2+ G+	20	mA
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2+ G-	30	mA
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2- G-	30	mA
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2- G+	-	mA
I <sub>H</sub>	Holding Current	V <sub>D</sub> =12V, I <sub>GT</sub> =0.1A	30	mA
V <sub>T</sub>	On-state Voltage	I <sub>T</sub> =25A	1.5	V
V <sub>GT</sub>	Gate Trigger Voltage	V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2+ G+	1.5	V
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2+ G-	1.5	V
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2- G-	1.5	V
		V <sub>D</sub> =6V, R <sub>L</sub> =10Ω, T2- G+	-	V
I <sub>D</sub>	Off-state Leakage Current	V <sub>D</sub> =V <sub>DRM</sub>	500	uA

### Static Characteristics

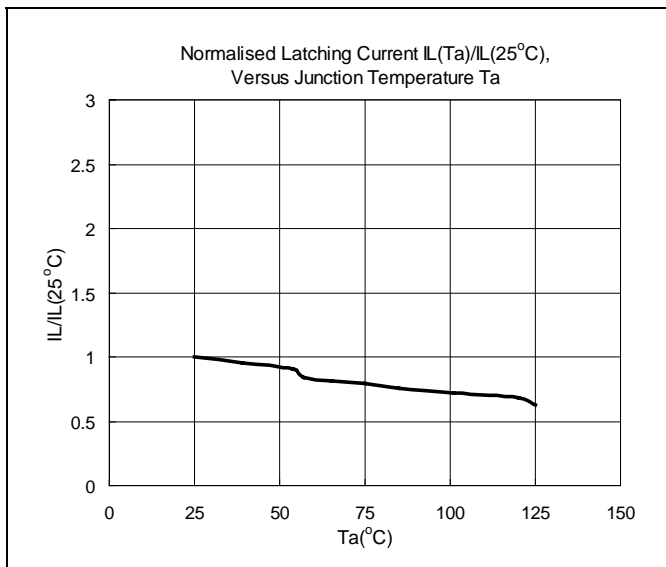
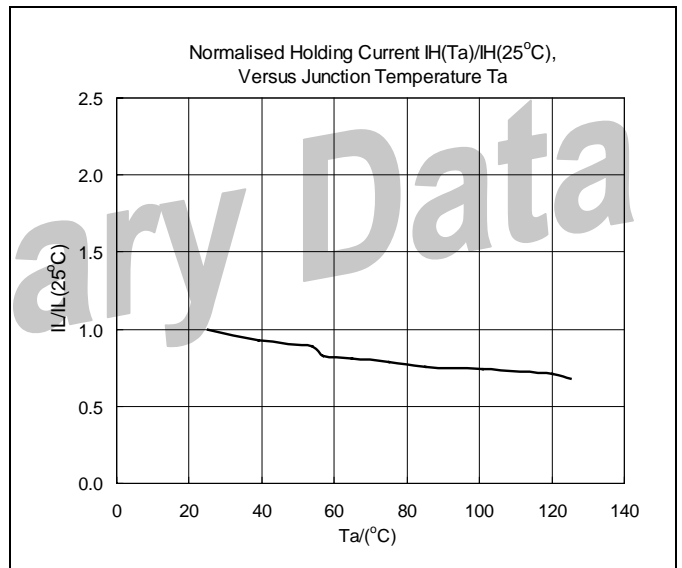
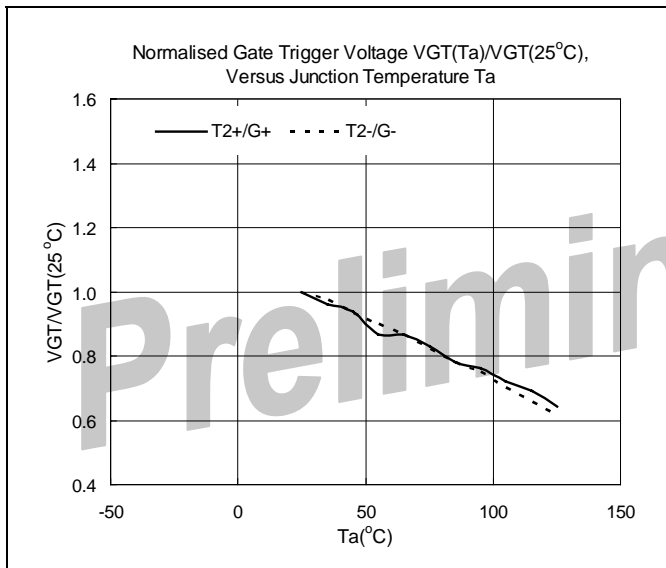
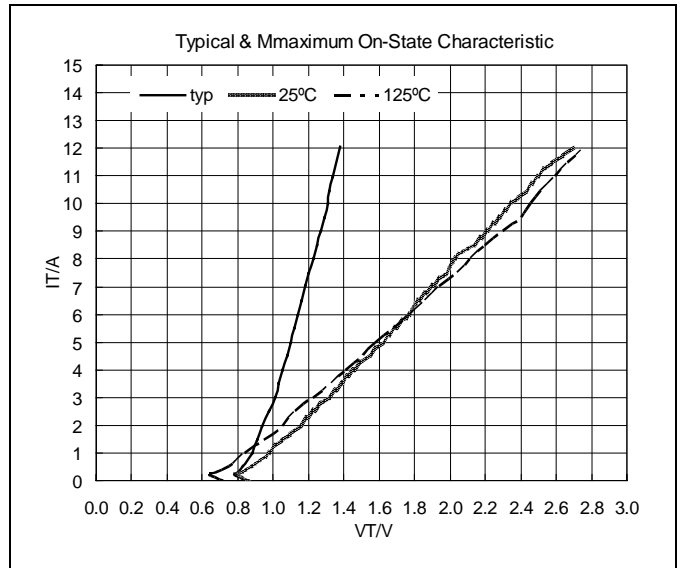
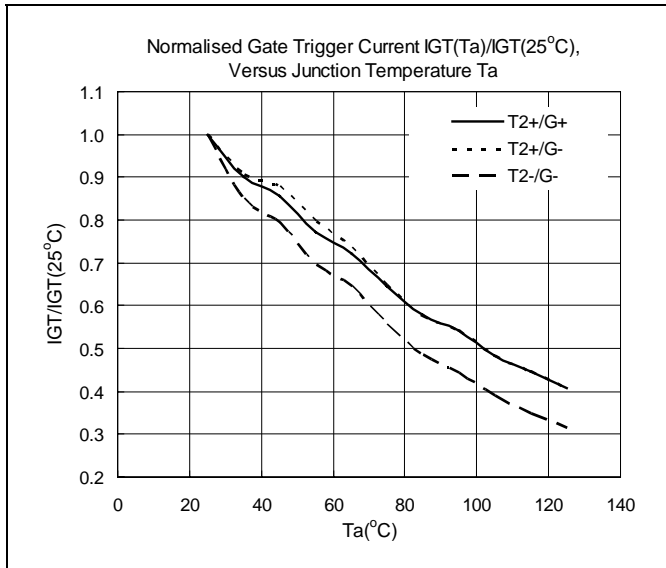
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	V <sub>DM</sub> =67% V <sub>DRM(max)</sub> ; T <sub>j</sub> = 125°C; exponential waveform; gate open circuit	-	50	-	V/us
tgt	Gate controlled turn-on time	I <sub>TM</sub> =6A; V <sub>D</sub> =V <sub>DRM(max)</sub> ; I <sub>G</sub> =0.1A; dI <sub>G</sub> /dt=5A/us	-	2	-	us

### Thermal Resistances

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Rth j-mb	Thermal resistance junction to mounting base	Full cycle Half cycle In free air	-	-	1.2	K/W
Rth j-a	Thermal resistance junction to ambient		-	-	1.7	K/W
			-	60	-	K/W

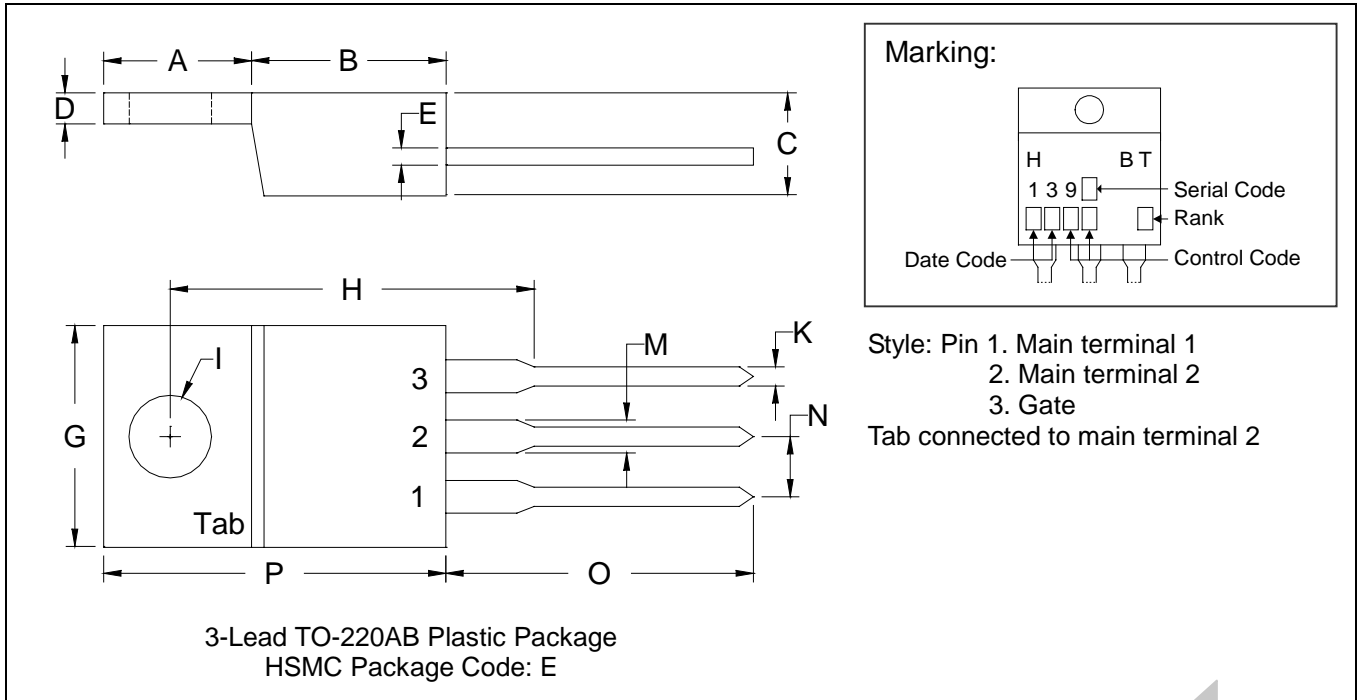


### Characteristics Curve





### TO-220AB Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

**Notes:**

- 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
- 2.Controlling dimension: millimeters.
- 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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